

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **HUI-MEI CHEN, CHIEN-KANG CHOU, JIN-YUAN LEE, HSIEN-TSUNG LIU**

For: **METHOD FOR IMPROVING SEMICONDUCTOR WAFER TEST ACCURACY**

Enclosed are:

**3** sheets of drawing(s) - formal.

An assignment of the invention to **Magic Corporation**

An associate power of attorney  Applicant claims small entity status

Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	Fee
<b>BASIC FEE</b>				<b>\$ 385.</b>
<b>TOTAL CLAIMS</b>	<b>14 -20=</b>	<b>0</b>	<b>x 9 =</b>	<b>\$ 0.</b>
<b>INDEP CLAIMS</b>	<b>2 -3=</b>	<b>0</b>	<b>x 43 =</b>	<b>\$ 0.</b>
		<b>SUB TOTAL</b>		<b>\$ 385.</b>
		<b>ASSIGNMENT</b>		<b>\$40.</b>
		<b>TOTAL</b>		<b>\$ 425.</b>

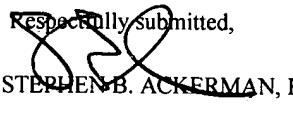
Please charge my Deposit Account No. 19-0033 in the amount of **\$ 425.** A duplicate copy of this sheet is enclosed.

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Any additional filing fees required under 37 CFR §1.16.

Any patent application processing fees under 37 CFR §1.17.

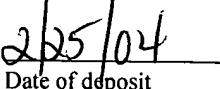
Respectfully submitted,

  
**STEPHEN B. ACKERMAN, REG. NO. 37,761**

**EXPRESS MAIL CERTIFICATE**

Express Mail No. **EV385357862US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Washington, DC 20231. Applicant and/or Attorney requests the date of deposit as the Filing Date.

  
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